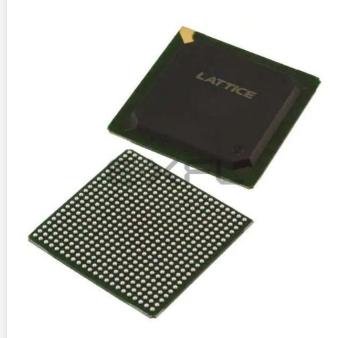
Lattice Semiconductor Corporation - <u>LFEC33E-3F484I Datasheet</u>



Welcome to **E-XFL.COM**

Understanding <u>Embedded - FPGAs (Field Programmable Gate Array)</u>

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	32800
Total RAM Bits	434176
Number of I/O	360
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	484-BBGA
Supplier Device Package	484-FPBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfec33e-3f484i

Email: info@E-XFL.COM

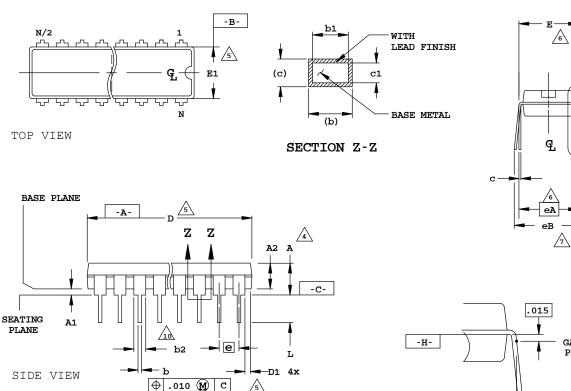
Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

SEE DETAIL



20-Pin Plastic DIP Package

Dimensions in Inches



NOTES:

- 1. CONTROLLING DIMENSION: INCH.
- 2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M
- 3. DISTANCE BETWEEN LEADS INCLUDING DAMBAR
- PROTRUSIONS TO BE .005 MINIMUM. DIMENSIONS A, A1 & L ARE MEASURED WITH THE PACKAGE SEATED IN JEDEC SEATING
- PLANE GAUGE GS-3.
- PLANE GAGE GS-3.

 DIMENSIONS D, D1 AND E1
 DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS.

 MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED .010

 6 E AND eA MEASURED WITH THE LEADS CONSTRAINED

 TO BE PERPENDICULAR TO DATUM C-
- 70 BE PERPENDICULAR TO DATOM.

 eB AND eC ARE MEASURED AT THE LEAD TIPS

 with the Leads unconstrained. 8 N IS THE MAXIMUM NUMBER OF LEAD
- POSITIONS.

 9. POINTED OR ROUNDED LEAD TIPS ARE PREFERRED TO EASE INSERTION
- 10 b2 MAXIMUM DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED .010
- 11 DATUM PLANE -H- COINCIDENT WITH THE BOTTOM OF LEAD , WHERE LEAD EXITS BODY

-Н-	GAGE
	→ ← eC

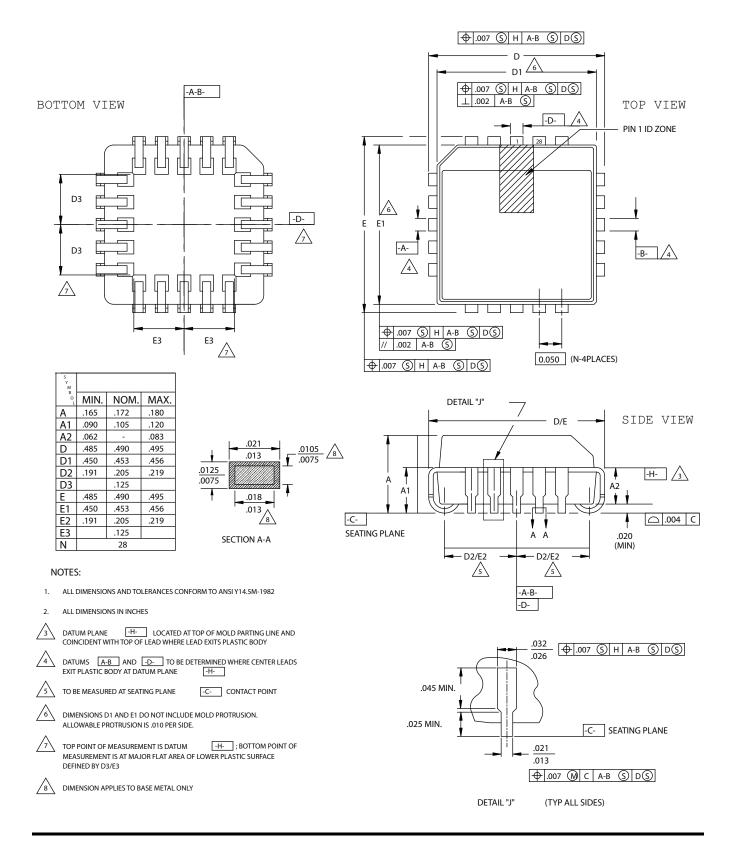
DETAIL A

	N = 20			
s Y M B	I	NCHES		N O T
o L	MIN.	NOM.	MAX.	TE
Α	-	ı	.210	4
A 1	.015	-	-	4
A 2	.115	.130	.195	
b	.014	.018	.022	
b1	.014	.018	.020	
b2	.045	.060	.070	10
С	.008	.008 .010 .014		
C1	.008	.010 .011		
D	.980	1.030	1.060	5
D1	.005	1	-	5
E	.300	.310	. 325	6
E1	.240	.250	.280	5
е	.100 BSC			
еA	.300 BSC			6
eВ	-	430		
еC	.000	.000060		
L	.115	.130	.150	4



28-Pin PLCC Package

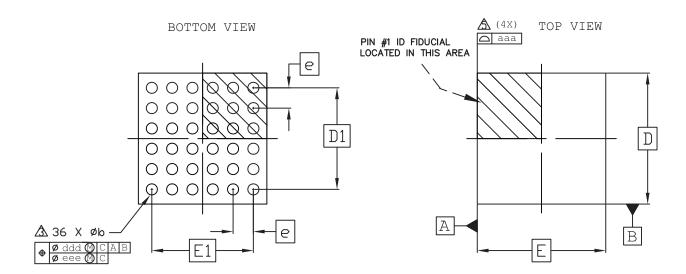
Dimensions in Inches

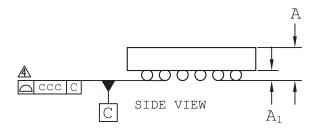




36-Ball WLCS Package Option 3: LIFMD™

Dimensions in Millimeters





NOTES:

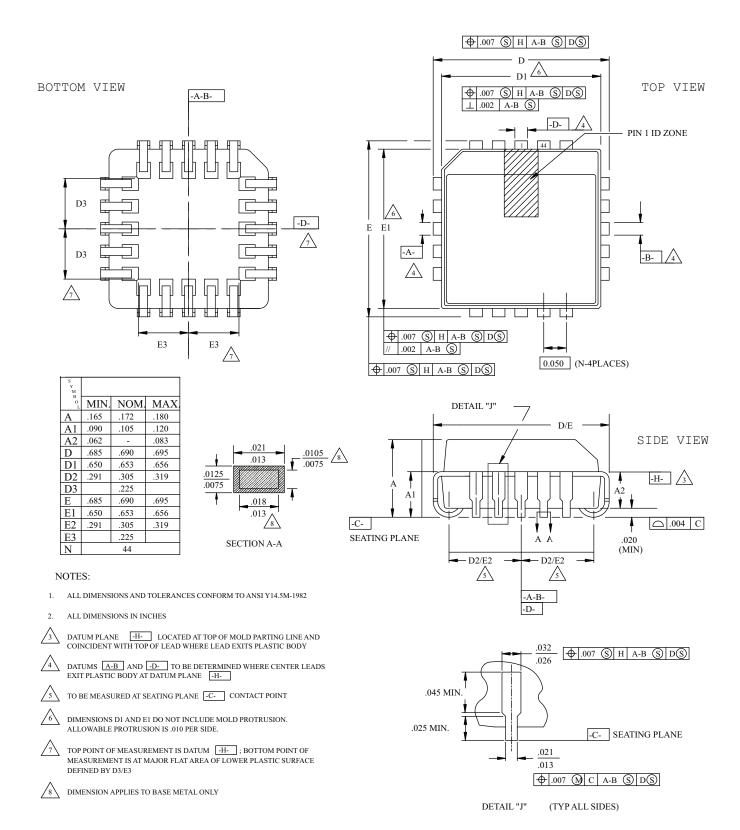
- 1. ALL DIMENSIONS AND TOLERANCE PER ASME Y 14.5M 1994.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.
- △ DIMENSION "b" IS MEASURES AT THE MAXIMUM BUMP DIAMETER PARALLEL TO PRIMARY DATUM C.
- \triangle PRIMARY DATUM $\boxed{\text{C}}$ AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
- \triangle BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

REF.	Min.	Nom.	Max.
А	-	-	0.600
A1	0.113	-	-
b	0.188	0.218	0.248
D	:	2.535 BS	С
E		2.583 BS	С
D1	2.00 BSC		
E1	2.00 BSC		
е	0.40 BSC		
aaa	0.030		
ccc	0.050		
ddd	0.050		
eee	0.015		



44-Pin PLCC Package

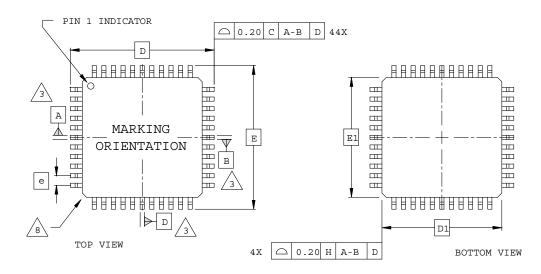
Dimensions in Inches

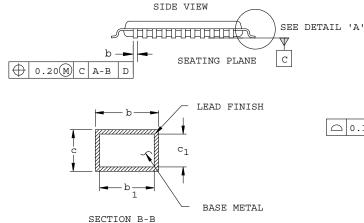


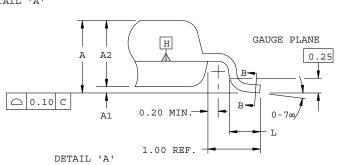


44-Pin TQFP Package (1.4 mm thick)

Dimensions in Millimeters







NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\stackrel{\textstyle >}{\scriptstyle 3}$ datums a, b and d to be determined at datum plane H.

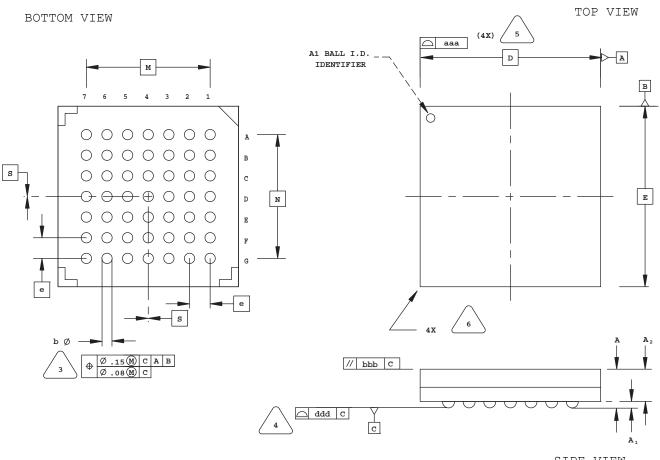
- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5. THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 6. SECTION B-B:
 THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE
 LEAD BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP.
- 7. A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.

/8\ EXACT SHAPE OF EACH CORNER IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.	
A	=	-	1.60	
A1	0.05	-	0.15	
A2	1.35	1.40	1.45	
D		12.00 BSC		
D1		10.00 BSC		
E		12.00 BSC		
E1		10.00 BSC		
L	0.45	0.60	0.75	
N	44			
е		0.80 BSC		
b	0.30	0.37	0.45	
b1	0.30	0.35	0.40	
С	0.09	0.15	0.20	
c1	0.09	0.13	0.16	



Dimensions in Millimeters



SIDE VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES 1. PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS. 2.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



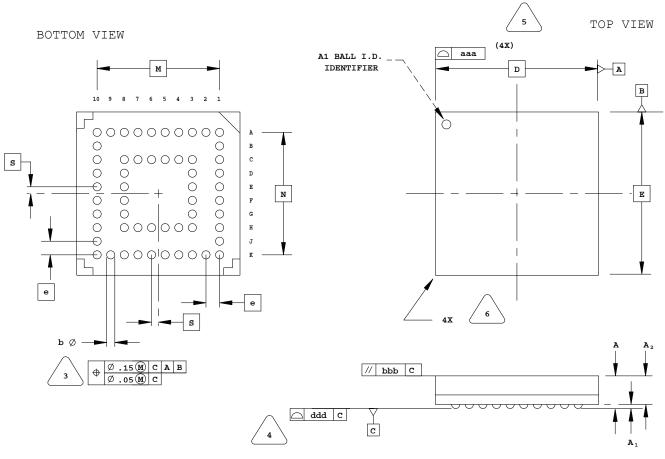
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.	
A	1.30	1.40	1.50	
A1	0.31	0.36	0.41	
A2	0.99	1.04	1.09	
D/E	7	.00 BSC		
M/N	4	4.80 BSC		
s		0 BSC		
b	0.40	0.46	0.52	
е	0	.80 BSC		
aaa	-	-	0.10	
bbb	-	-	0.10	
ddd	-	-	0.12	



Dimensions in Millimeters



SIDE VIEW

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM $\[\]$



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



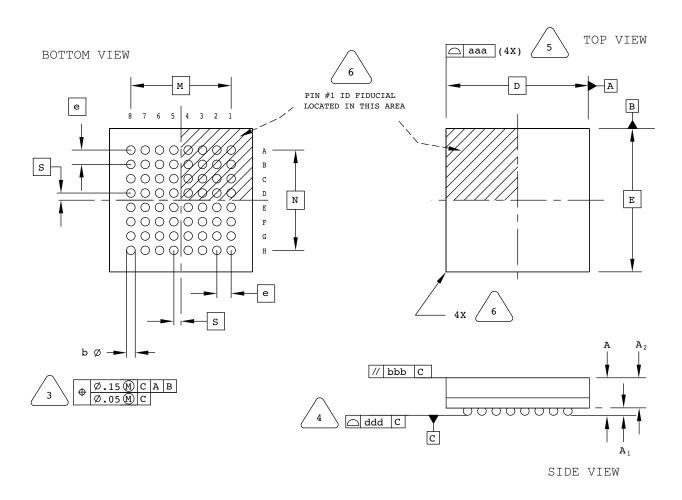
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.	
A	1.10	1.23	1.35	
A1	0.15	-	-	
A2	-	-	1.10	
D/E	6	.00 BSC		
M/N	4	4.50 BSC		
s	0	0.25 BSC		
b	0.25	0.30	0.35	
е	0	.50 BSC		
aaa	-	-	0.10	
bbb	-	-	0.10	
ddd	-	-	0.08	



Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

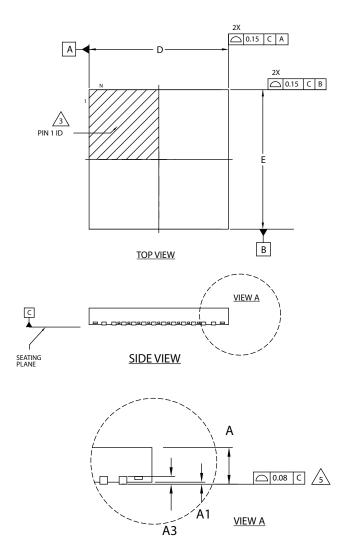


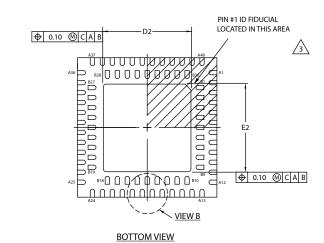
SYMBOL	MIN.	NOM.	MAX.	
A	0.90	1.00	1.10	
A1	0.15	-	-	
A2	-	-	0.85	
D/E	5	.00 BSC		
M/N	3.50 BSC			
S	0	0.25 BSC		
b	0.25	0.30	0.35	
е	0	0.50 BSC		
aaa	_	_	0.10	
bbb	_	_	0.10	
ddd	_	_	0.08	

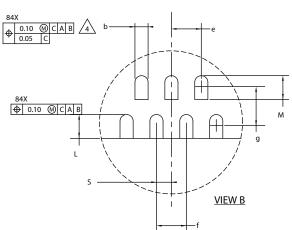


84-Pin QFN Package

Dimensions in Millimeters







SYMBOL MIN. NOM. MAX. 0.75 0.95 0.85 Α1 0.00 0.02 0.05 АЗ 0.15 REF D 7.0 BSC D2 4.50 Ε 7.0 BSC E2 4.30 4.50 0.17 0.27 b 0.22 0.50 BSC f 0.50 BSC g 0.65 BSC S 0.25 BSC $_{\rm L}$ 0.30 0.40 0.50 Μ 0.30 0.50 0.40

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.

 $\sqrt{3}$

EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.



DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM TERMINAL TIP.

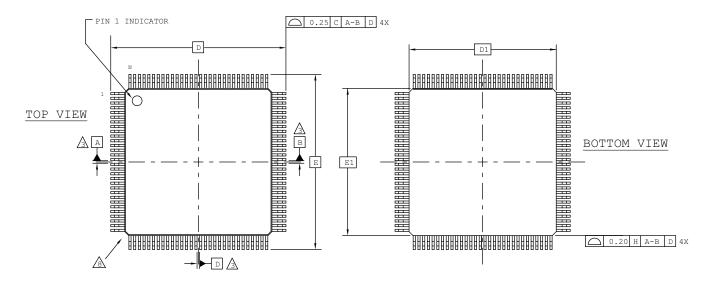


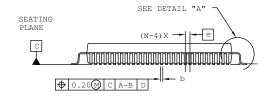
APPLIES TO EXPOSED PORTION OF TERMINALS.

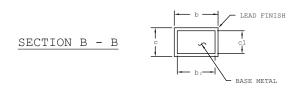


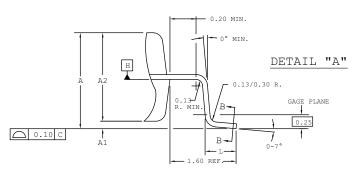
120-Pin PQFP Package

Dimensions in Millimeters









NOTES:

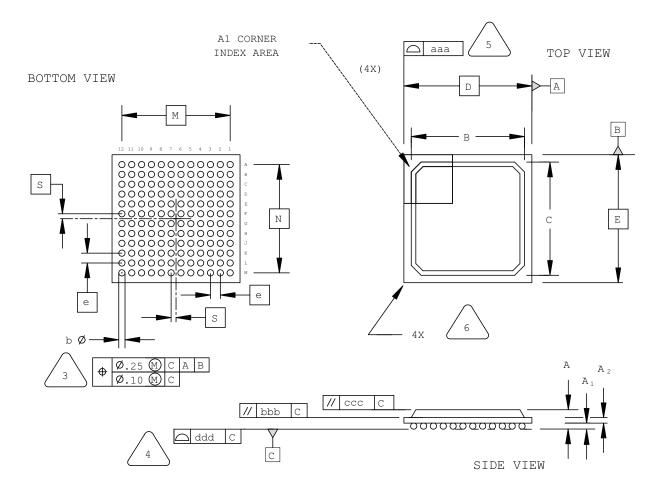
- 1.0 DIMENSIONING AND TOLERANCING PER ANSI Y14.5 1982.
- 2.0 ALL DIMENSIONS ARE IN MILLIMETERS.
- A DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
- 4.0 DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION IS 0.254 MM ON D1 AND E1 DIMENSIONS.
- 5.0 THE TOP OF PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15 MM.
- 7.0 A1 IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- $\stackrel{\textstyle \wedge}{\underline{\mathop{\otimes}}}$ exact shape of each corner is optional.
- SEXACT SHAPE OF EXPOSED HEATSINK IS OPTIONAL.

SYMBOL	MIN.	NOM.	MAX.
A	-	-	4.10
A1	0.25	-	0.50
A2	3.20	3.40	3.60
D		31.20 BSC	!
D1		28.00 BSC	
E		31.20 BSC	!
E1	28.00 BSC		
L	0.73	0.88	1.03
N	120		
е	0.80 BSC		
b	0.29	-	0.45
b1	0.29	0.35	0.41
С	0.11	-	0.23
c1	0.11	0.15	0.19



144-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



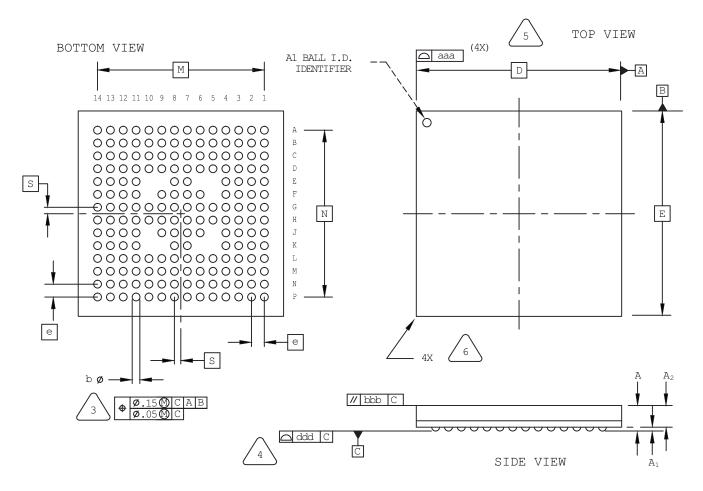
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.	
А	1.30	1.70	2.10	
A1	0.30	0.50	0.70	
A2	0.30	0.50	0.70	
B/C	11.00	11.60	12.20	
D/E	13	3.00 BSC		
M/N	11.00 BSC			
S		0.50 BSC		
b	0.50	0.60	0.70	
е	1	.00 BSC		
aaa	-	-	0.20	
bbb	_	-	0.25	
ccc	-	-	0.35	
ddd	-	-	0.20	



Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

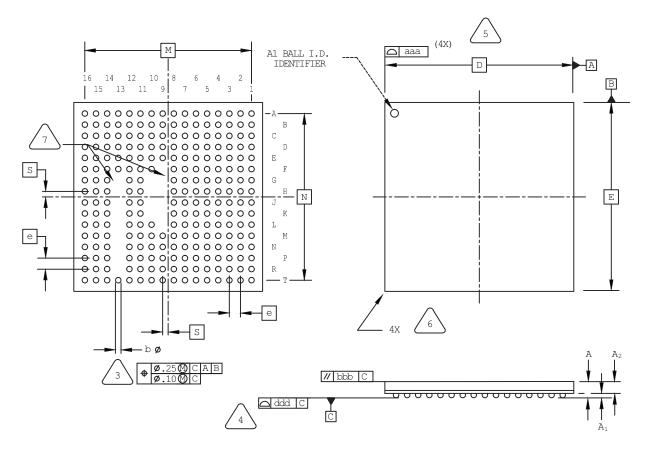


SYMBOL	MIN.	NOM.	MAX.	
А	1.20	1.35	1.50	
A1	0.16	_	-	
A2	_	_	1.34	
D/E	8	.00 BSC		
M/N	6.50 BSC			
S	0	0.25 BSC		
b	0.25	0.30	0.35	
е	0.50 BSC			
aaa	_	_	0.10	
bbb	_	_	0.10	
ddd	_	_	0.08	



237-Ball ftBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.



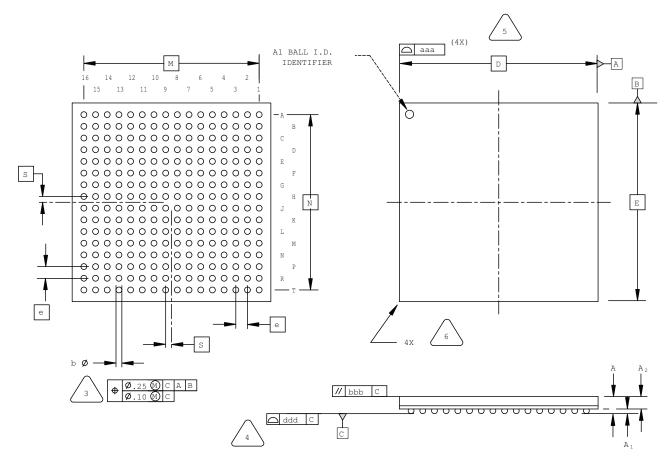
DEPOPULATED 13G TO 13R, 10G TO 10K, AND 9F TO 9L.

MIN.	NOM.	MAX.
1.40	1.55	1.70
0.30	-	-
_	-	1.24
1	7.0 BSC	
15.0 BSC		
0.50 BSC		
0.40	0.50	0.60
1.0 BSC		
_	-	0.20
_	-	0.25
_	-	0.15
	1.40 0.30 - 1.0 0.40	1.40 1.55 0.30 - 17.0 BSC 15.0 BSC 0.50 BSC 0.40 0.50



256-Ball ftBGA Package Option 1: ispMACH 4000, MachXO, LatticeXP2

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



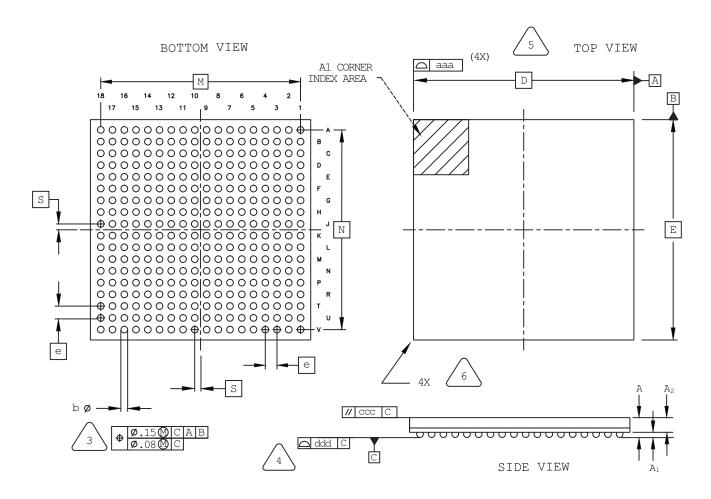
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.
А	1.25	1.40	1.55
A1	0.30	-	-
A2	-	-	1.25
D/E	17.0 BSC		
M/N	15.0 BSC		
S	0.50 BSC		
b	0.40	0.50	0.60
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ddd	-	-	0.12



Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



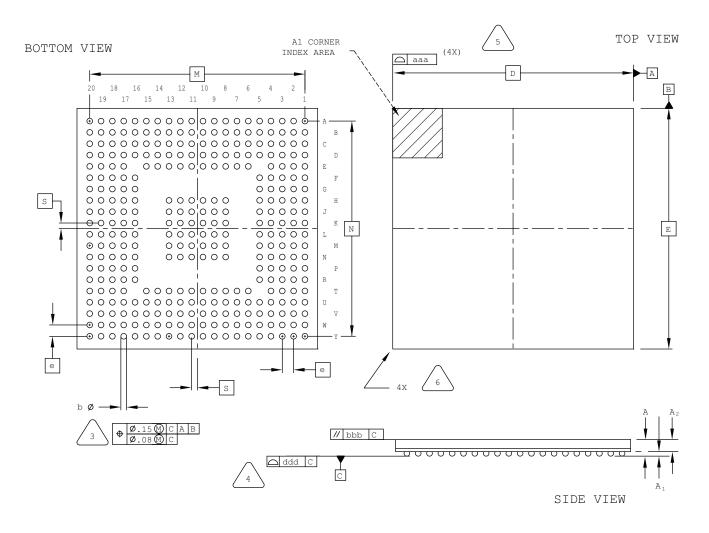
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.
А	-	-	1.70
A1	0.25	0.35	-
A2	0.80	1.00	_
D/E	15.0 BSC		
M/N	13.6 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
е	0.80 BSC		
aaa	_	_	0.15
ccc	_	_	0.20
ddd	_	_	0.20



Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING
PLANE ARE DEFINED BY THE SPHERICAL
CROWNS OF THE SOLDER BALLS.



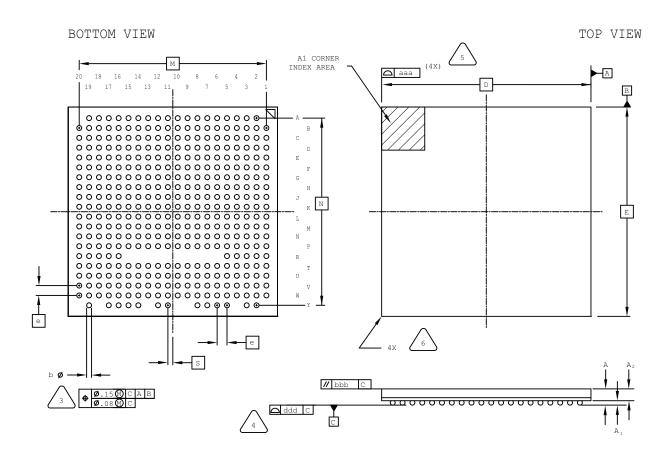
BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.
А	-	-	2.00
A1	0.25	_	_
A2	0.65	_	_
D/E	17.0 BSC		
M/N	15.2 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
е	0.80 BSC		
aaa	-	-	0.15
bbb	_	_	0.20
ddd	_	_	0.20



Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

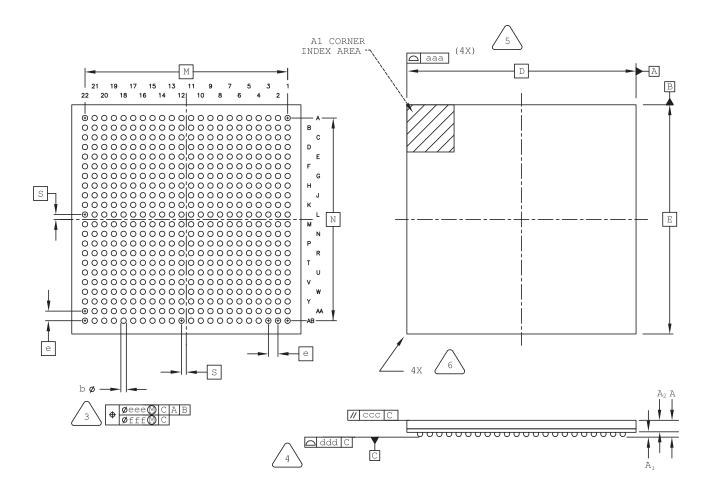


SYMBOL	MIN.	NOM.	MAX.
А	ı	-	1.76
A1	0.25	0.30	0.35
A2	0.80	-	ı
D/E	17.00 BSC		
M/N	15.20 BSC		
S	0.40 BSC		
b	0.35	0.40	0.45
е	0.80 BSC		
aaa	_	-	0.15
bbb	-	-	0.20
ddd	-	_	0.12



484-Ball caBGA Package (19x19 mm Body)

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



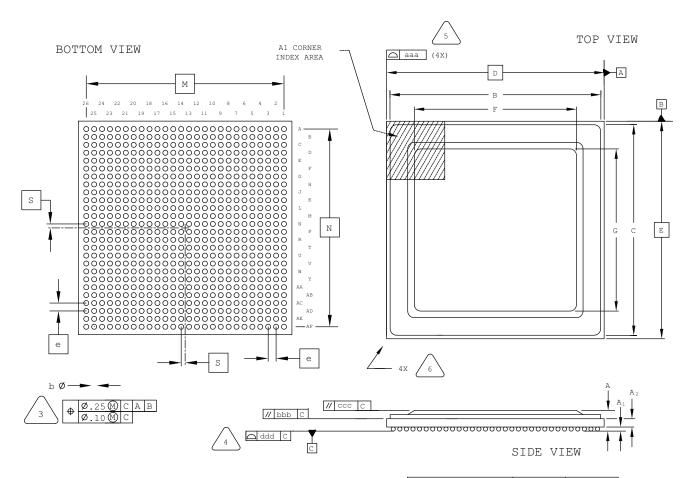
EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.

7 JEDEC REFERENCE: MO-275A

SYMBOL	MIN.	NOM.	MAX.
А	-	_	1.70
A1	0.25	-	-
A2	0.65	-	_
D/E	19.0 BSC		
M/N	16.8 BSC		
S	0.40 BSC		
b	0.40	0.45	0.50
е	0.80 BSC		
aaa	_	-	0.15
ccc	_	_	0.20
ddd	_	_	0.20
eee	_	_	0.15
fff	_	_	0.08



Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.

2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.

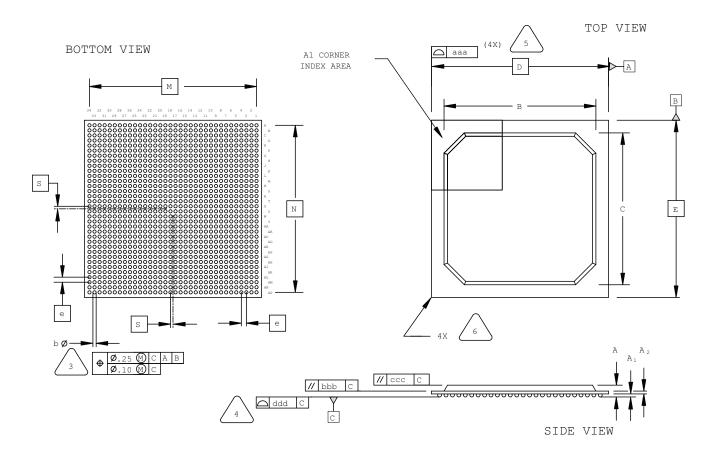


SYMBOL	MIN.	NOM.	MAX.
A	2.55	2.90	3.25
A1	0.40	0.50	0.60
A2	1	1.20 REF	
B/C	26.55	26.60	26.65
D/E	27.00 BSC		
F/G	18.55	18.60	18.65
M/N	25.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	_	_	0.20



1156-Ball fpBGA Package

Dimensions in Millimeters



NOTES: UNLESS OTHERWISE SPECIFIED

- 1. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- 2. ALL DIMENSIONS ARE IN MILLIMETERS.



DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C



PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.



SYMBOL	MIN.	NOM.	MAX.
A	1.90	2.25	2.60
A1	0.30	0.50	0.70
A2	0.40	0.60	0.80
B/C	29.80	30.30	30.80
D/E	35.00 BSC		
M/N	33.00 BSC		
S	0.50 BSC		
b	0.50	0.60	0.70
е	1.00 BSC		
aaa	-	-	0.20
bbb	-	-	0.25
ccc	-	-	0.35
ddd	-	-	0.20